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HDI PCB Market: Trends, Opportunities and Competitive Analysis [2024-2030]

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Abstracts

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HDI PCB Market Trends and Forecast

The future of the global high-density interconnect (HDI) PCB market looks promising with opportunities in the smartphone, computer, telecom and datacom, consumer electronics, and automotive industries. The global HDI PCB market is expected t%li%reach an estimated $20.8 billion by 2030 with a CAGR of 4.8% from 2024 t%li%2030. The major drivers for this market are growth in consumer electronics market, miniaturization of electronic devices, and increasing demand for high performance devices.

Lucintel forecasts that 4-6 layers will remain the largest segment due t%li%increasing demand in smartphones and telecommunication equipment. The 10+ layer HDI PCB market is expected t%li%witness the highest growth during the forecast period due t%li%the growing demand for smart wearables and connected devices.

Smartphones will remain the largest end use industry due t%li%the increasing demand for high performance PCB and growing demand for more space in smartphones for larger batteries. Automotive is expected t%li%witness the highest growth over the forecast period due t%li%advancement in automotive electronics.

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Asia Pacific will remain the largest market, and it is als%li%expected t%li%witness the highest growth over the forecast period due t%li%the increasing electronic content in automotive and growth in consumer electronic devices & telecommunication products.

Asia Pacific will remain the largest market in the HDI PCB Market

1. United States: Companies like Intel Corporation, Apple Inc., and Qualcomm Incorporated are leading initiatives in HDI PCB technology. The US government's focus on promoting innovation in semiconductor manufacturing drives research and development in HDI PCBs for applications in smartphones, laptops, and automotive electronics.

2. China: Chinese companies such as Huawei Technologies Co., Ltd., Tencent Holdings Limited, and Xiaomi Corporation are prominent players in the market. China's government support for the semiconductor industry and initiatives like the "Made in China 2025" plan drive the adoption of HDI PCB technology for telecommunications, consumer electronics, and automotive applications.

3. Germany: Companies like Bosch GmbH, Siemens AG, and Infineon Technologies AG are significant in the market. Germany's government initiatives t%li%promote Industry 4.0 and digitalization drive innovation in HDI PCBs for smart manufacturing and automotive electronics.

4. Taiwan: Taiwanese companies such as Taiwan Semiconductor Manufacturing Company Limited (TSMC) and Foxconn Technology Group play a key role in HDI PCB manufacturing. Taiwan's government support for the semiconductor industry and investment in technology research accelerates advancements in HDI PCB technology for various electronic devices.

5. Japan: Companies like Sony Corporation, Panasonic Corporation, and Canon Inc. are active in the HDI PCB market. Japan's government investment in technology research and collaboration with companies promote the development of HDI PCBs for consumer electronics, medical devices, and automotive systems.

Emerging Trends in the HDI PCB Market

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Emerging trends, which have a direct impact on the dynamics of the industry, include miniaturization of electronic devices and growing demand for low loss/high-speed HDI PCBs.

A total of 99 figures / charts and 76 tables are provided in this 195-page report t%li%help in your business decisions. Sample figures with insights are shown below.

HDI PCB Market by Segment

The study includes trends and forecast for the global high density interconnect (HDI) PCB market by end use industry, technology, build-up layer count, and region as follows:

By End Use Industry [$M and Thousand Sqm shipment analysis for 2018 – 2030]:

- Smartphones and Tablets
- Computers
- Telecom/Datacom
- Consumer Electronics
- Automotive
- Others

By Technology [$M and Thousand Sqm shipment analysis for 2018 – 2030]:

- 4-6 Layer
- 8-10 Layer
- 10+ Layer

By Build-Up Structure [$M and Thousand Sqm shipment analysis for 2018 – 2030]:

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1+n+1

2+n+2

3+n+3

Others

By Region [$M and Thousand Sqm shipment analysis for 2018 – 2030]:

North America

Europe

Asia Pacific

The Rest of the World

List of HDI PCB Companies

Companies in the market compete on the basis of product quality offered. Major players in this market focus on expanding their manufacturing facilities, R&D investments, infrastructural development, and leverage integration opportunities across the value chain. With these strategies HDI PCB companies cater increasing demand, ensure competitive effectiveness, develop innovative products & technologies, reduce production costs, and expand their customer base. Some of the HDI PCB companies profiled in this report includes.

TTM Technologies, Inc.

Tripod Technology Corporation

AT&S

Kingboard Holdings Ltd.

CCTC

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DG Shengyi Electronics

Dynamic Electronics Co. Ltd.

Gold Circuit Electronics

Olympic

DAP

Unimicron Technology Corp.

Compeq Manufacturing Co., Ltd.

Ibiden Co., Ltd.

Zhen Ding Technology Holding Limited

Unitech

Samsung Electro-Mechanics

Meik%li%Electronics Co. Ltd

Recent Developments in the HDI PCB Market

1. Rising Demand for HDI PCBs in Consumer Electronics: The demand for HDI PCBs continues t%li%grow in the consumer electronics sector, driven by trends such as miniaturization, increased functionality, and higher performance requirements. Manufacturers are witnessing a surge in orders for HDI PCBs used in smartphones, tablets, wearable devices, and other portable electronics. The adoption of advanced HDI technologies, including laser drilling and sequential lamination, enables the production of ultra-compact PCB designs with improved signal integrity and reliability.

2. Expansion of HDI PCB Production Capacity: Leading PCB manufacturers are expanding their production capacity for HDI PCBs t%li%meet growing demand from various end-use industries. Companies are investing in new manufacturing facilities,

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equipment upgrades, and process optimizations t%li%increase output and improve efficiency. The expansion of production capacity is aimed at addressing market demand for high-density, high-performance PCB solutions and supporting the development of next-generation electronic devices.

3. Focus on Advanced HDI Technologies: PCB manufacturers are focusing on advancing HDI technologies t%li%meet the evolving requirements of modern electronic devices. Recent developments include innovations in laser drilling, microvia formation, and interconnection techniques t%li%achieve higher layer counts, finer trace/space widths, and improved signal integrity. These technological advancements enable the development of HDI PCBs with enhanced electrical performance, thermal management, and reliability, supporting the design and production of cutting-edge electronics.

4. Rise of HDI PCBs in Automotive Applications: HDI PCBs are gaining traction in automotive applications, driven by the increasing adoption of advanced driver-assistance systems (ADAS), infotainment systems, and electric vehicle (EV) technology. Automakers are leveraging HDI PCBs t%li%enable compact and lightweight electronic modules that deliver superior performance and reliability in harsh automotive environments. The use of HDI technology allows for the integration of complex functionalities int%li%smaller form factors, supporting the development of smarter and more connected vehicles.

5. Demand for HDI PCBs in 5G Infrastructure: The rollout of 5G networks is fueling demand for HDI PCBs in telecommunications infrastructure equipment, including base stations, antennas, and routers. HDI PCBs play a crucial role in supporting the high-speed, high-frequency requirements of 5G communication systems, enabling faster data transmission, lower latency, and greater network capacity. Manufacturers are ramping up production of HDI PCBs optimized for 5G applications, incorporating advanced materials and design techniques t%li%meet the stringent performance criteria of next-generation wireless networks.

Features of HDI PCB Market

Market Size Estimates: High Density Interconnect (HDI) PCB market size estimation in terms of value ($M) and Volume (Thousand Sqm)

Trend and Forecast Analysis: Market trends (2018-2023) and forecast (2024-2030) by various segments and regions.

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Segmentation Analysis: High Density Interconnect (HDI) PCB market size by various segments, such as end use industry, technology, and built-up structure, in terms of value and volume.

Regional Analysis: High Density Interconnect (HDI) PCB market breakdown by North America, Europe, Asia Pacific, and the Rest of the World.

Growth Opportunities: Analysis on growth opportunities in various end use industries, technologies, built-up structures, and regions for the high density interconnect (HDI) PCB market.

Strategic Analysis: This includes M&A, new product development, and competitive landscape for the high density interconnects (HDI) PCB market.

Analysis of competitive intensity of the industry based on Porter's Five Forces model.

FAQ

Q1. What is the HDI PCB market size?

Answer: The global HDI PCB market is expected t%li%reach an estimated $20.8 billion by 2030.

Q2. What is the growth forecast for HDI PCB market?

Answer: The HDI PCB market is expected t%li%grow at a CAGR of 4.8% from 2024 t%li%2030.

Q3. What are the major drivers influencing the growth of the HDI PCB market?

Answer: The major drivers for this market are growth in the consumer electronics market, miniaturization of electronic devices, and increasing demand for high performance devices.

Q4. What are the major applications or end use industries for HDI PCB?

Answer: Smart phones and tablets, and computers are the major end use industries for

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HDI PCB market.

Q5. What are the emerging trends in HDI PCB market?

Answer: Emerging trends, which have a direct impact on the dynamics of the industry, include miniaturization of electronic devices and growing demand for low loss/high-speed HDI PCBs.

Q6. Wh%li%are the key HDI PCB companies?

Answer: Some of the key HDI PCB companies are as follows:

TTM Technologies, Inc.

Tripod Technology Corporation

AT&S

Kingboard Holdings Ltd.

CCTC

DG Shengyi Electronics

Dynamic Electronics Co. Ltd.

Gold Circuit Electronics

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Zhen Ding Technology Holding Limited

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Samsung Electro-Mechanics

Meik%li%Electronics Co. Ltd

Q7.Which HDI PCB technology segment will be the largest in future?

Answer: Lucintel forecasts that 4-6 layers will remain the largest segment due t%li%increasing demand in smartphone and telecom and datacom. The 10+ layer HDI PCB market is expected t%li%witness the highest growth during the forecast period due t%li%the growing demand for smart wearables and connected devices.

Q8: In HDI PCB market, which region is expected t%li%be the largest in next 5 years?

Answer: Asia Pacific is expected t%li%remain the largest region and witness the highest growth over next 5 years.

Q9. D%li%we receive customization in this report?

Answer: Yes, Lucintel provides 10% Customization Without any Additional Cost.

This report answers following 11 key questions

Q.1 What are some of the most promising potential, high-growth opportunities for the global high density interconnect (HDI) PCB market by end use industry (smartphones and tablets, computers, telecom/datacom, consumer electronics, automotive and others), technology (4-6 layer, 8-10 layer, 10+ layer), build-up layer count (1+n+1, 2+n+2, 3+n+3, and others), and region (North America, Europe, Asia Pacific, and the Rest of the World)?

Q.2 Which segments will grow at a faster pace and why?

Q.3 Which regions will grow at a faster pace and why?

Q.4 What are the key factors affecting market dynamics? What are the drivers and challenges of the High Density Interconnect (HDI) PCB market?

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Q.5 What are the business risks and threats t%li%the high density interconnect (HDI) PCB market?

Q.6 What are the emerging trends in the high density interconnect (HDI) PCB market and the reasons behind them?

Q.7 What are some changing demands of customers in the high density interconnect (HDI) PCB market?

Q.8 What are the new developments in the high density interconnect (HDI) PCB market? Which companies are leading these developments?

Q.9 Wh%li%are the major players in the high density interconnect (HDI) PCB market? What strategic initiatives are being implemented by key players for business growth?

Q.10 What are some of the competitive products and processes in the high density interconnect (HDI) PCB market, and how big of a threat d%li%they pose for loss of market share via material or product substitution?

Q.11 What M&A activities did take place in the last five years in the high density interconnect (HDI) PCB market?

For any questions related t%li%High Density Interconnect (HDI) PCB market or related t%li%High Density Interconnect (HDI) PCB market share, High Density Interconnect (HDI) PCB market analysis, and High Density Interconnect (HDI) PCB market size, write t%li%Lucintel analysts at helpdesk@lucintel.com. We will be glad t%li%get back t%li%you soon.

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Market

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